

ABSTRACT

An optical module (100) and an optical communication device. The optical module (100) comprises a first housing (110), a second housing (120), an optoelectronic component (130) and a circuit board (140). The optoelectronic component (130) and the circuit board (140) are both mounted between the first housing (110) and the second housing (120). A bottom wall (150) on the side of the first housing (110) facing the second housing (120) is provided with a first protrusion (111), the first protrusion (111) being provided with a first matching surface (112); and a bottom wall (150) of the second housing (120) is provided with a second matching surface (122), the first matching surface (112) being thermally connected to the second matching surface (122). Heat generated by the optoelectronic component (130) during operation can be conducted to the first housing (110) by means of the first protrusion (111), and heat concentrated on the second housing (120) can also be conducted to the first housing (110) by means of the first protrusion (111) and can be conducted to the outside by means of the bottom wall (150) of the first housing (110). Compared with a traditional air heat conduction method, the contact area between the first housing (110) and the second housing (120) is increased, such that the heat conduction rate is accelerated, and the heat concentrated on the second housing (120) can thus be quickly dissipated, thereby significantly improving the heat dissipation effect of the optical module (100).

Fig. 1